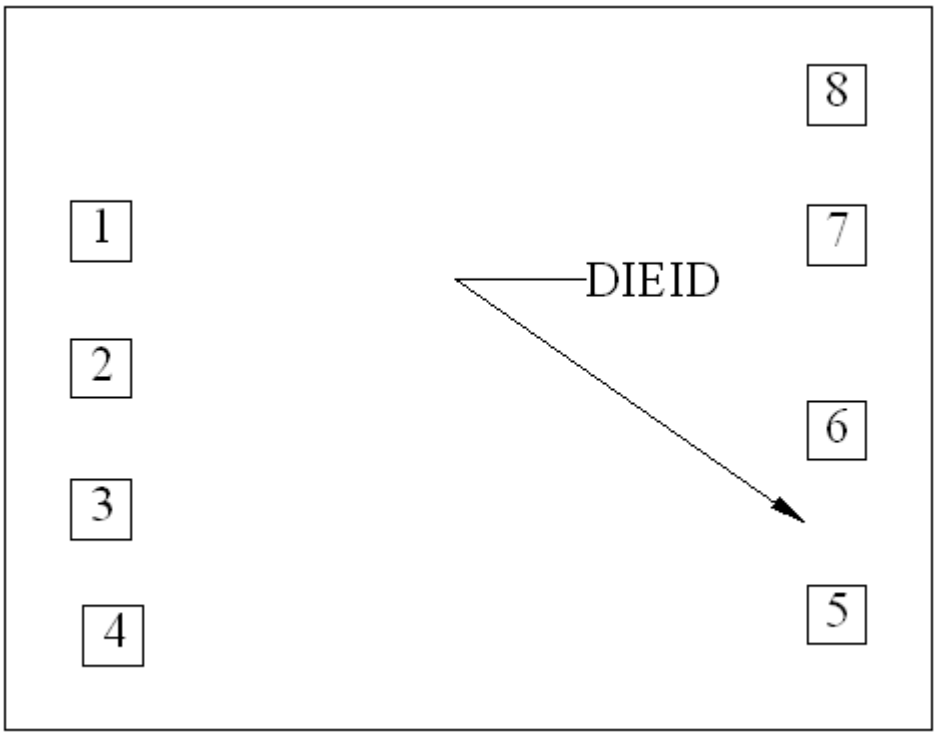
LMV762 MDC MWC
LOW VOLTAGE, PRECISION COMPARATOR WITH PUSH-PULL OUTPUT

April 08,2004

DIE LAYOUT (B-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMV762B	Bond Pad Opening Size (min)	88µm x 88µm
Die Step	B	Bond Pad Metalization	0.5%COPPER,1%SILICON,BAL. ALUMINUM,
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1372µm x 1067µm 54.0mils x 42.0mils	Back Side Connection	Floating
Thickness	216µm Nominal		
Min Pitch	185µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
OUTPUT A	1	-544	203	88	x	88
INPUT A -	2	-544	0	88	x	88
INPUT A+	3	-544	-209	88	x	88
V -	4	-526	-395	88	x	88
INPUT B+	5	544	-364	88	x	88
INPUT B -	6	544	-92	88	x	88
OUTPUT B	7	544	196	88	x	88
V+	8	544	404	88	x	88

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